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Bare Die and Wafer Part Numbering & Packing Guide

Central™
Semiconductor Corp.

www.centrasemi.com

Bare Die Part Numbering System

- This specification defines the method for bare die packing and part number identification.
Example: Bipolar Power NPN Darlington Transistor Die, 2N6300, with optional up-screening to MIL-PRF-38534 Class H equivalent, Tray (Waffle) Package.

CP127 - H2N6300 - CM

DEVICE TYPE NUMBER
(10 ALPHA/NUMERIC MAX)

PREFIX FOR OPTIONAL UP-SCREENING*

H = MIL-PRF-38534 Class H equivalent
 K = MIL-PRF-38534 Class K equivalent
 HC = MIL-PRF-19500 JANHC equivalent
 KC = MIL-PRF-19500 JANKC equivalent
 CEN = Customer-specific up-screening

*Non up-screened devices will not include this prefix.

CENTRAL PROCESS NUMBER
(5 - 7 ALPHA/NUMERIC)

CPxxx = Transistor
 CPZxx = Zener Diode
 CPDxx = Diode
 CPQxx = TRIAC
 CPSxx = SCR
 CPCxx = Silicon Carbide

PACKING METHOD

CM = Singulated bare die,
 100% electrically tested,
 100% visually inspected,
 reject die removed,
 tray (waffle) package

CT = Singulated bare die,
 100% electrically tested,
 reject die removed,
 tray (waffle) package

WN = Wafer form,
 100% electrically tested,
 reject die inked

WR = Wafer form,
 100% electrically tested,
 sawn and mounted on adhesive
 membrane and plastic ring,
 reject die inked

WS* = Wafer form,
 100% electrically tested,
 sawn and mounted on adhesive
 membrane and metal frame,
 reject die inked

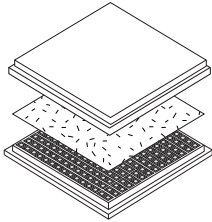
***WS is by special order only.**
 Please contact Central sales
 representative at 631-435-1110.

Visit the Central website for a complete
 listing of all available WR and WS
 specifications:

www.centalsemi.com/bare-die



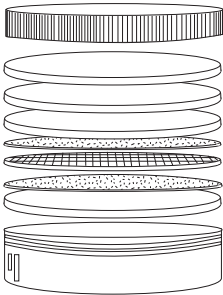
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

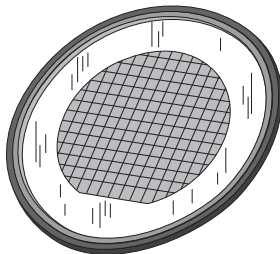
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

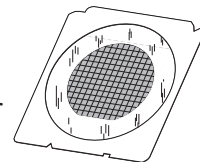
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centalsemi.com/bdspecs

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PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

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- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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